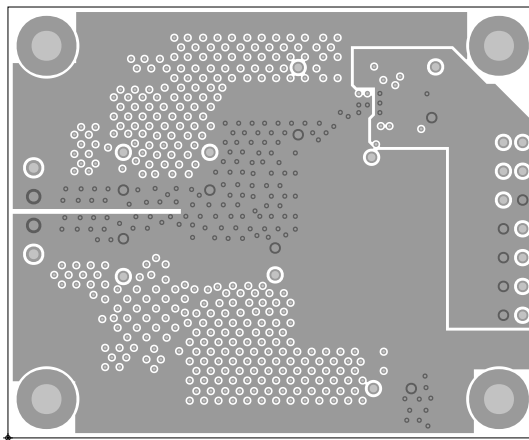
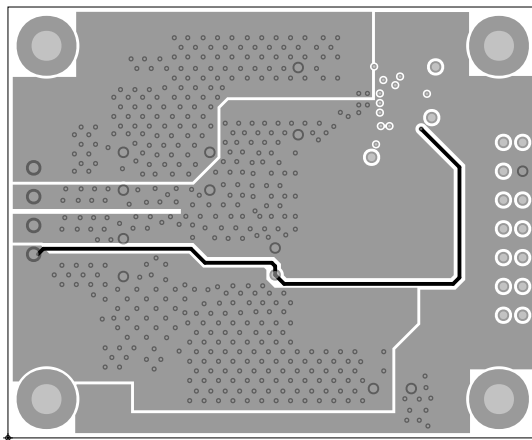


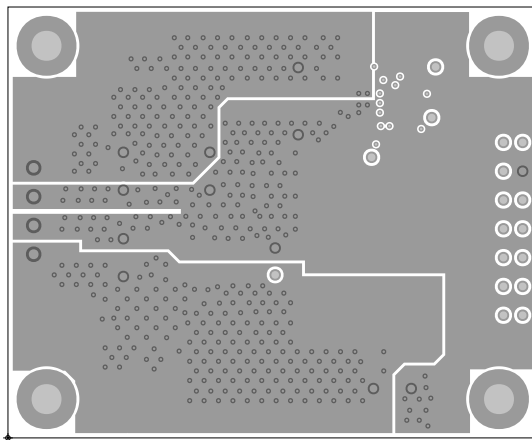
	LAYER: 01 PRIMARY-SIDE	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
	DESIGNER: TD	PROJECT NAME: SIC46 UNIFIED HIGH POWER		
	CHECKER: INITIAL			
	DATE: 26AUG17	PROJECT NUMBER:	REV.	
	JOB#:	NUMBER	3	
		TOLERANCES		
		DECIMAL	ANGLE	
		X ± .1	± 5	
		XX ± .01	MACH FINISH	
		XXX ± .005	✓	



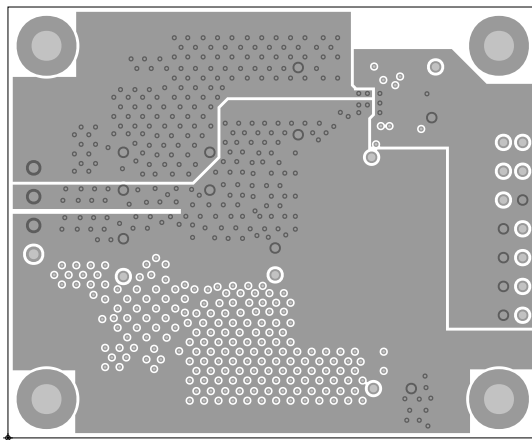
	INNER_LAYER2	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES  TOLERANCES DECIMAL      ANGLE X ± .1          ± 5 XX ± .01      MACH FINISH XXX ± .005    ✓
	DESIGNER: TD	PROJECT NAME: SIC46 UNIFIED HIGH POWER		
	CHECKER: INITIAL	PROJECT NUMBER:		
	DATE: 26AUG17	NUMBER	REV. 3	
	JOB#:			



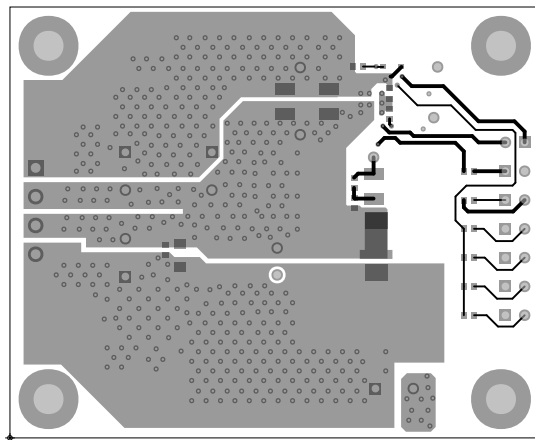
	INNER_LAYER3	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES	
	DESIGNER: TD	PROJECT NAME: SIC46 UNIFIED HIGH POWER			
	CHECKER: INITIAL	PROJECT NUMBER:		TOLERANCES DECIMAL      ANGLE X ± .1      ± 5 XX ± .01      MACH FINISH XXX ± .005      ✓	
	DATE: 26AUG17	NUMBER			
	JOB#:	REV. 3			



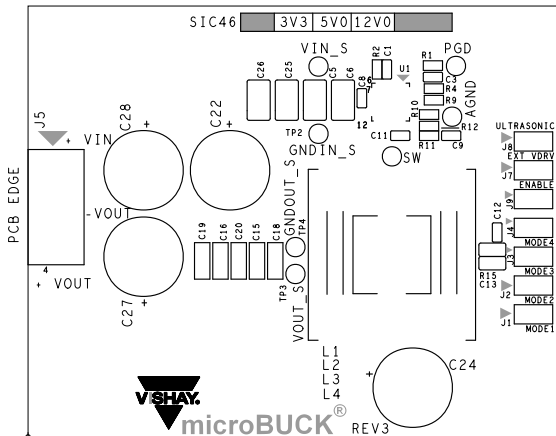
	INNER_LAYER4	COMPANY NAME: Vishay/Siliconix	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES  TOLERANCES DECIMAL      ANGLE X ± .1      ± 5 XX ± .01      MACH FINISH XXX ± .005      ✓
	DESIGNER: TD	PROJECT NAME: SIC46 UNIFIED HIGH POWER	
	CHECKER: INITIAL	PROJECT NUMBER: NUMBER	
	DATE: 26AUG17	REV. 3	
	JOB#:		

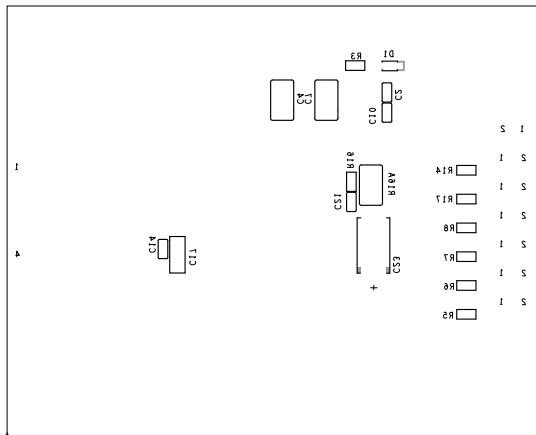


	INNER_LAYER5	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES	
	DESIGNER: TD	PROJECT NAME: SIC46 UNIFIED HIGH POWER			
	CHECKER: INITIAL	PROJECT NUMBER:		TOLERANCES DECIMAL      ANGLE X ± .1            ± 5 XX ± .01        MACH FINISH XXX ± .005      ✓	
	DATE: 26AUG17	NUMBER			
	JOB#:	REV. 3			

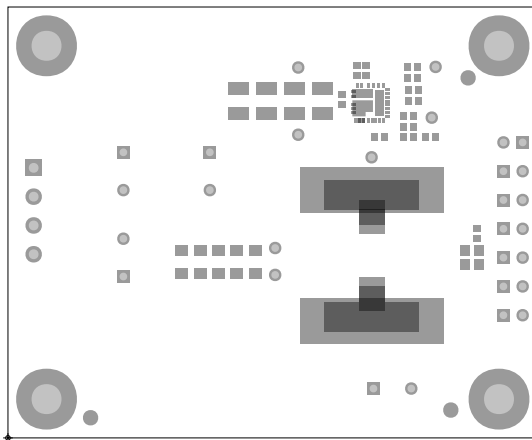


JOB#: DATE: 28AUG17 CHECKER: INITIAL DESIGNER: TD	SECONDARY-SIDE		LAYER: 06		COMPANY NAME: Vishay Siliconix PROJECT NAME: SIC46 UNIFIED HIGH POWER PROJECT NUMBER: NUMBER
REV.		3	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMAL X ± .1 XX ± .01 XXX ± .002 MACH FINISH ✓		

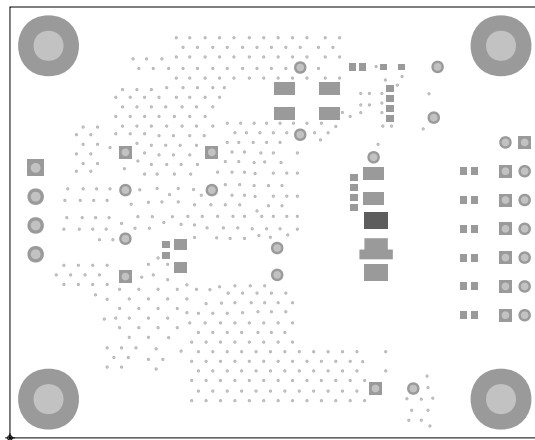




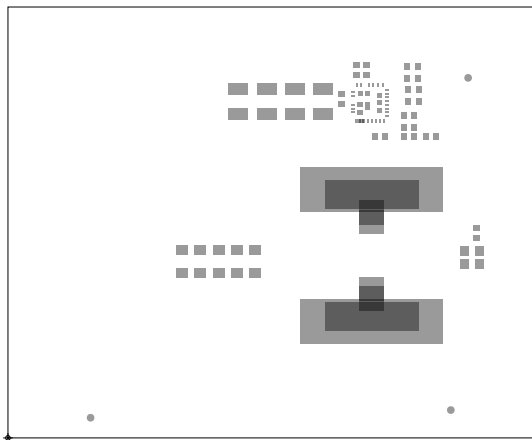




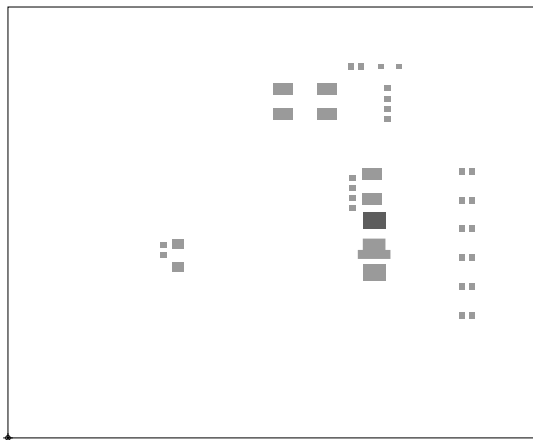
	SOLDERMASK PRIMARY-SIDE	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES  TOLERANCES DECIMAL      ANGLE X ± .1          ± 5 XX ± .01      MACH FINISH XXX ± .005      ✓
	DESIGNER: TD	PROJECT NAME: SIC46 UNIFIED HIGH POWER		
	CHECKER: INITIAL	PROJECT NUMBER:		
	DATE: 26AUG17	NUMBER	REV. 3	
	JOB#:			



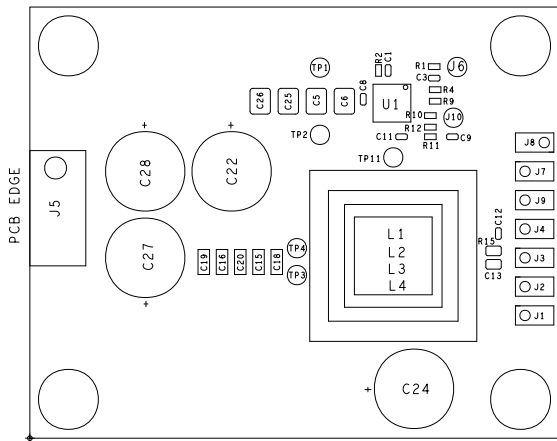
JOB#: DATE: 28AUG17 CHECKER: INITIAL DESIGNER: TD	SECONDARY-SIDE		COMPANY NAME: Vishay\Siliconix	
	PROJECT NUMBER:		PROJECT NAME: SIC46 UNIFIED HIGH POWER	
	REV. 3		TOLERANCES	
			DECIMAL X ± .1 ANGLE ± 2 MACH FINISH ✓ XXX ± .002	
			UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES	



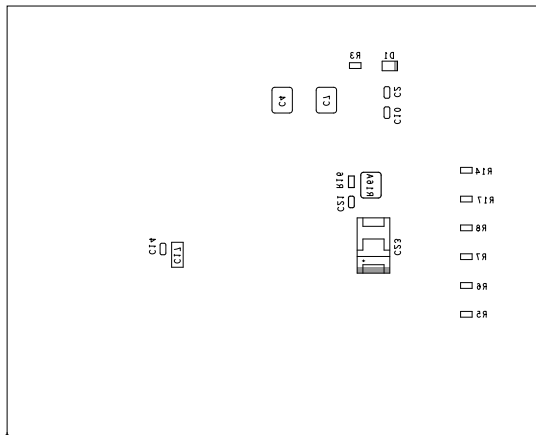
	PASTEMASK PRIMARY-SIDE	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES  TOLERANCES DECIMAL      ANGLE X ± .1          ± 5 XX ± .01      MACH FINISH XXX ± .005    ✓
	DESIGNER: TD	PROJECT NAME: SIC46 UNIFIED HIGH POWER		
	CHECKER: INITIAL			
	DATE: 26AUG17	PROJECT NUMBER:	REV.	
	JOB#:	NUMBER	3	



JOB#: DATE: 28AUG17 CHECKER: INITIAL DESIGNER: TD SECONDARY-SIDE PASTEMASK	COMPANY NAME: Vishay\siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMAL X ± .1 ANGLE ° ± .5 MACH FINISH XXX ± .002 ✓
	PROJECT NAME: SIC46 UNIFIED HIGH POWER		
	PROJECT NUMBER:	REV.	
	NUMBER	3	

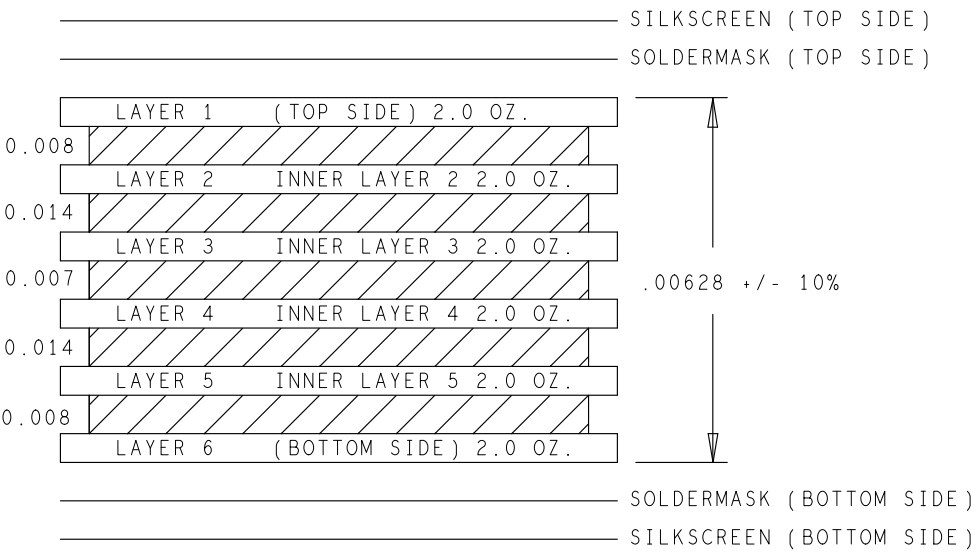


# ASSEMBLY TOP



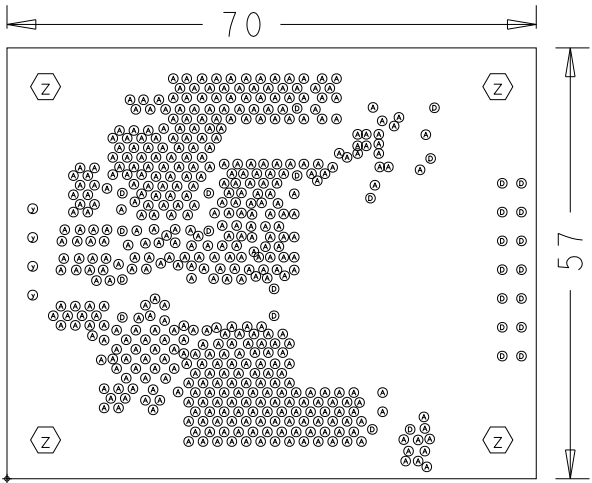
# ASSEMBLY BOTTOM

LAYER DETAIL  
6 LAYER



DRILL CHART: TOP to BOTTOM  
ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
⊙	13.0	+3.0/-13.0	PLATED	467
⊙	40.0	+3.0/-3.0	PLATED	29
⊙	51.0	+3.0/-3.0	PLATED	4
⊞	156.0	+3.0/-3.0	PLATED	4



FAB NOTE

REVISIONS

REV	DESCRIPTION	DATE	APPROVED

FAB NOTES:UNLESS OTHERWISE SPECIFIED.

- PART NUMBER P/N 133-020-0002
- SIDE SHOWN PRIMARY / SIDE 1.
- DIMENSIONS DECIMAL INCHES.
- BASE MATERIAL LEAD-FREE PROCESS
- T<sub>g</sub> MINIMUM GLASS TRANSITION TEMPERATURE (T<sub>g</sub>) OF 170 DEGREES CELSIUS.
- FLAME CLASS UL 94V-0 & MUST MEET REQUIREMENTS OF UL 796.
- MOT MANUFACTURE MUST BE UL RECOGNIZED TO PRODUCE THIS PRODUCT SUCH THAT IT MEETS 130 DEGREES CELSIUS MAXIMUM OPERATING TEMPERATURE (MOT).
- MARKINGS THE FOLLOWING MUST BE MARKED OR ETCHED ON SIDE 2 OF PCB IN AREA SHOWN:  
DATE CODE.  
UL RECOGNIZED VENDOR ID UL TYPE DESIGNATION AND/OR MARKINGS WHICH REPECT THE SPECIFIED FLAME CLASS AND MAXIMUM OPERATING TEMPERATURE RATINGS.
- PCB THICKNESS 0.62 +/-10% AS MESURED OVER METAL.
- BOW & TWIST SHALL BE DETERMINED BY PHYSICAL MEASUREMENT AND PERCENTAGE CALCULATION IN ACCORDANCE WITH IPC - TM - 650. METHOD 2.4.22.
- PLATING MINIMUM COPPER THICKNESS AFTER PROCESSING INTERNAL AND EXTERNAL LAYERS IS PROVIDED BELOW IN THE LAYER STACKUP.  
HOLE PLATING = 0.001 MIN. AVERAGE / 0.0008 ABSOLUTE MIN PLATING.  
HOLE DIAMETERS SPECIFIED AFTER PLATING (SEE HOLE SCHEDULE).
- CONDUCTORS FINISHED CONDUCTOR WIDTH: 0.010 REDUCED NO MORE THAN 20% OF NOMINAL.  
FINISHED CONDUCTOR SPACING: 0.003 MINIMUM.
- ANNULAR RING 0.001 MINIMUM FOR INTERNAL ANNULAR RING.  
0.002 MINIMUM FOR EXTERNAL ANNULAR RING.
- Minimum immersion gold thickness of 2uin - 8uin over a minimum of 118uin electroless nickel.
- When applies Gold Plating and Nickel Plating For Edge-Board Connectors and Non-Soldered Areas Shall be Per IPC-2221  
Unless Otherwise Specified on the Fabrication Drawing.  
For none functional short gold fingers it is ok to leave the plating trace

- 16.SOLDER MASK TO BE IN ACCORDANCE WITH IPC-SM-840C CLASS T.  
TYPE: LIQUID PHOTOIMAGEABLE.  
BRAND: CIBA-GEIGY PROBIMER 52, 65M, ENTHONE ENPLATE DSR-3241 OR EQUIVALENT.  
FINISH: MATTE FINISH PREFERRED.  
COLOR: LIGHT BLUE (OR CLOSEST)  
REGISTRATION: TO BE WITHIN +/-0.003 OF ITS RESPECTIVE OUTER CIRCUIT LAYERS.  
SOLDER MASK ENCROACHMENT ONTO SMT LANDS IS INTENTIONAL  
WHERE SUPPLIED DATA DOES NOT PROVIDE CLEARANCE FROM THE PAD.

- 17.SOLDER MASK COLOR:LIGHT BLUE (OR CLOSEST)

- 18.FINISH SOLDER MASK OVER BARE COPPER (SMOBC) WITH  
HOT AIR SOLDER LAVELING (HASL).

- 19.SILKSCREEN WHITE NONCONDUCTIVE INK.  
NO INK TO APPEAR ON EXPOSED COPPER SUCH AS PLATE THROUGH HOLE PADS AND  
SURFACE MOUNT LANDS. INK ON SOLDER MASK COVERED PADS IS PERMISSIBLE.
- 20.LAYER STACKUP 4 LAYERS. SEE STACK-UP DETAIL.

- 21.TOTAL THICKNESS 0.062".

- 22.FIDUCIALS ADD FIDUCIALS TO PRIMARY SIDES.

- 23 MATERIAL: LEAD-FREE PROCESS

- 24 COLOR: LIGHT BLUE (OR CLOSEST)

- 25 COPPER THICKNESS: SEE STACK-UP DETAIL.

	FAB DRAWING	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES  TOLERANCES DECIMAL ANGLE XX ± .01 ± .5 XXX ± .005 MACH FINISH ✓
	DESIGNER: TD	PROJECT NAME: SIC46_UNIFIED HIGH POWER		
	CHECKER: INITIAL	FAB NUMBER:		
	DATE: 26AUG17	REV. SHEET: NUMBER 3 1 OF 2		